SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	SMD Power Inductor	ABC'S DWG NO.	SQ3225□□□□2□-□□□		
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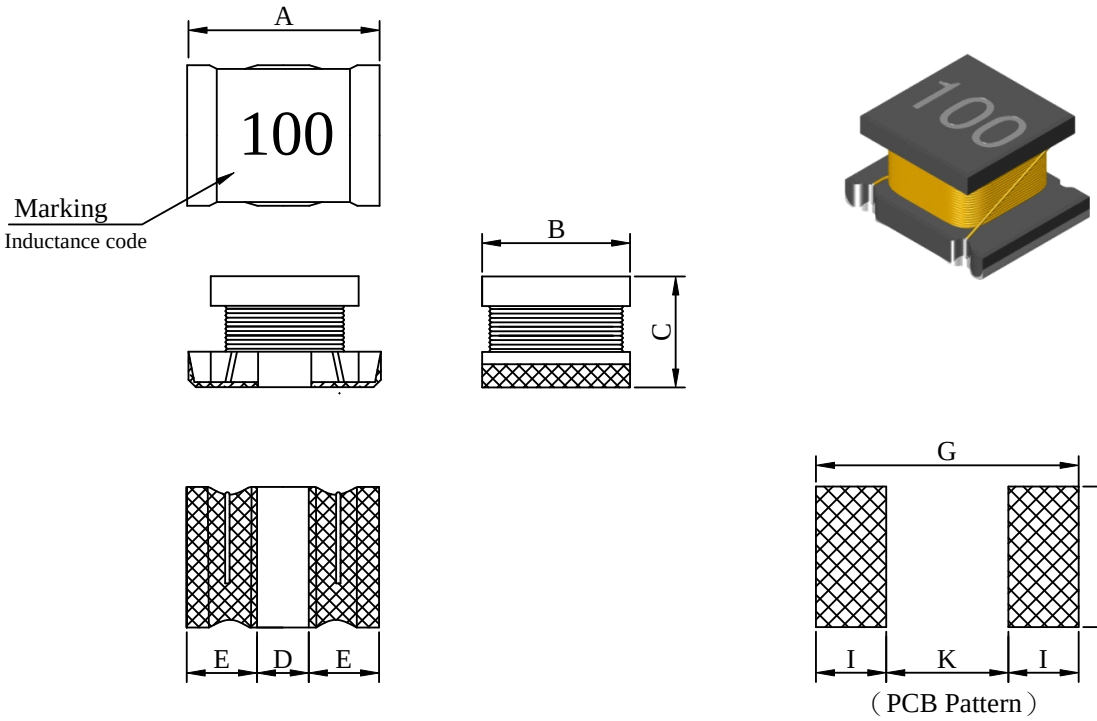
I．Configuration and dimensions：



Unit：mm

A	B	C	D	E	G	H	I	K
3.20 ±0.3	2.50 ±0.3	2.00 ±0.4	1.30 typ.	1.20 ref.	3.80 ref.	2.80 ref.	1.40 ref.	1.00 ref.

II．Description：

a．Ferrite drum core construction.

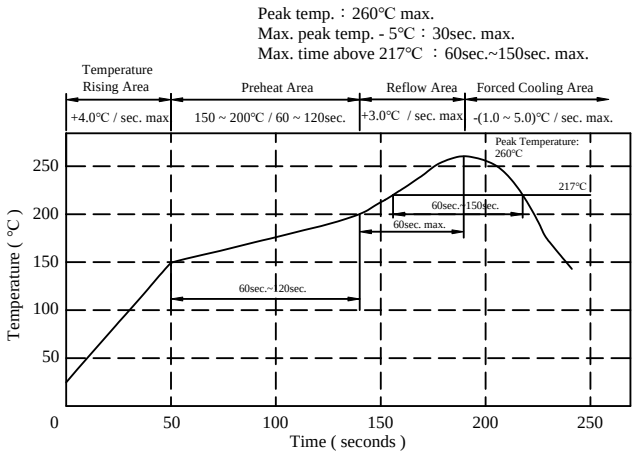
b．Enamelled copper wire：H class

c．Product weight：0.046 g（ref.）

d．Moisture sensitivity Level 1

e．Products comply with RoHS' requirements

f．Halogen free



III．General specification：

a．Storage temp.：-40℃ ----+125℃

b．Operating temp.：-40℃----+125℃

(Temp. rise included)

c．Resistance to solder heat：260℃.10 sec.

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IV．Electrical characteristics：

DWG. No.	Inductance (μH)	Test Freq. (Hz) L	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
SQ32251R0M2□ -□□□	1.00 ± 20%	1M	100.0	0.50	445
SQ32251R2M2□ -□□□	1.20 ± 20%	1M	100.0	0.60	425
SQ32251R5M2□ -□□□	1.50 ± 20%	1M	75.0	0.60	400
SQ32251R8M2□ -□□□	1.80 ± 20%	1M	60.0	0.70	390
SQ32252R2M2□ -□□□	2.20 ± 20%	1M	50.0	0.80	370
SQ32252R7M2□ -□□□	2.70 ± 20%	1M	43.0	0.90	320
SQ32253R3M2□ -□□□	3.30 ± 20%	1M	38.0	1.00	300
SQ32253R9M2□ -□□□	3.90 ± 20%	1M	35.0	1.10	290
SQ32254R7M2□ -□□□	4.70 ± 20%	1M	31.0	1.20	270
SQ32255R6M2□ -□□□	5.60 ± 20%	1M	28.0	1.30	250
SQ32256R8M2□ -□□□	6.80 ± 20%	1M	25.0	1.50	240
SQ32258R2M2□ -□□□	8.20 ± 20%	1M	23.0	1.60	225
SQ3225100K2□ -□□□	10.00 ± 10%	1M	20.0	1.80	190
SQ3225120K2□ -□□□	12.00 ± 10%	1M	18.0	2.00	180
SQ3225150K2□ -□□□	15.00 ± 10%	1M	16.0	2.20	170
SQ3225180K2□ -□□□	18.00 ± 10%	1M	15.0	2.50	165
SQ3225220K2□ -□□□	22.00 ± 10%	1M	14.0	2.80	150
SQ3225270K2□ -□□□	27.00 ± 10%	1M	13.0	3.10	125
SQ3225330K2□ -□□□	33.00 ± 10%	1M	12.0	3.50	115
SQ3225390K2□ -□□□	39.00 ± 10%	1M	11.0	3.90	110
SQ3225470K2□ -□□□	47.00 ± 10%	1M	11.0	4.30	100
SQ3225560K2□ -□□□	56.00 ± 10%	1M	10.0	4.90	85
SQ3225680K2□ -□□□	68.00 ± 10%	1M	9.0	5.50	80
SQ3225820K2□ -□□□	82.00 ± 10%	1M	8.5	6.20	70
SQ3225101K2□ -□□□	100.00 ± 10%	1M	8.0	7.00	80
SQ3225121K2□ -□□□	120.00 ± 10%	1M	7.5	8.00	75
SQ3225151K2□ -□□□	150.00 ± 10%	1M	7.0	9.30	70
SQ3225181K2□ -□□□	180.00 ± 10%	1M	6.0	10.20	65
SQ3225221K2□ -□□□	220.00 ± 10%	1M	5.5	11.80	65
SQ3225271K2□ -□□□	270.00 ± 10%	1M	5.0	12.50	65
SQ3225331K2□ -□□□	330.00 ± 10%	1M	5.0	13.00	65
SQ3225391K2□ -□□□	390.00 ± 10%	1M	5.0	22.00	50
SQ3225471K2□ -□□□	470.00 ± 10%	1k	5.0	25.00	45
SQ3225561K2□ -□□□	560.00 ± 10%	1k	5.0	28.00	40

1). Electrical specifications at 25℃

2). IDC base on Temp. rise 20℃ max. & △ L/L0A=10% max.

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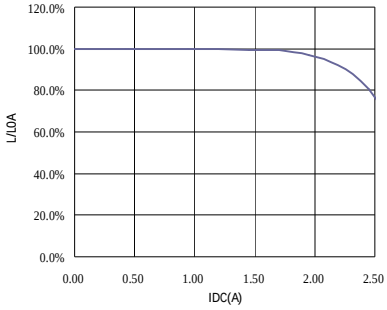
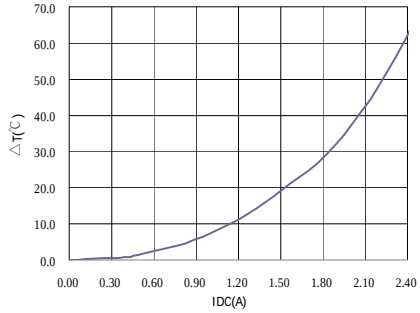
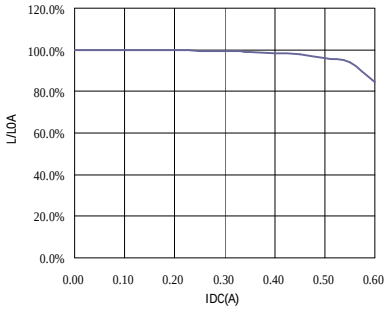
Ⅴ． Curve：

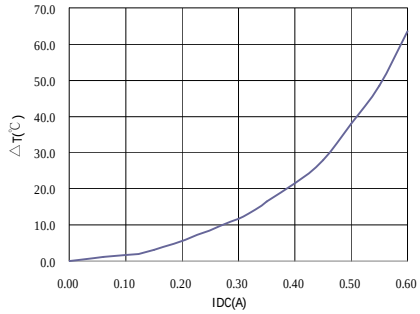
SQ32251R2M2□



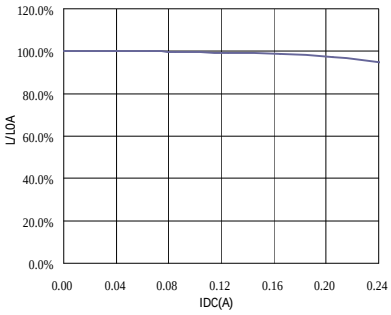


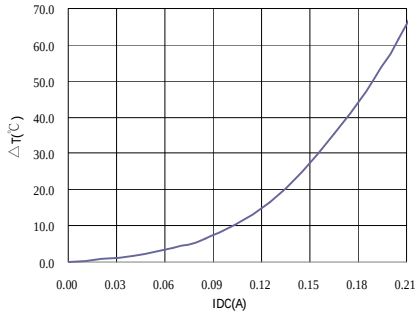
SQ3225220K2□



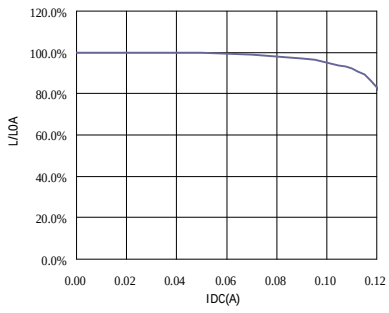


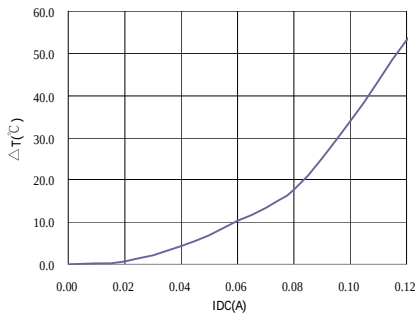
SQ3225221K2□





SQ3225561K2□





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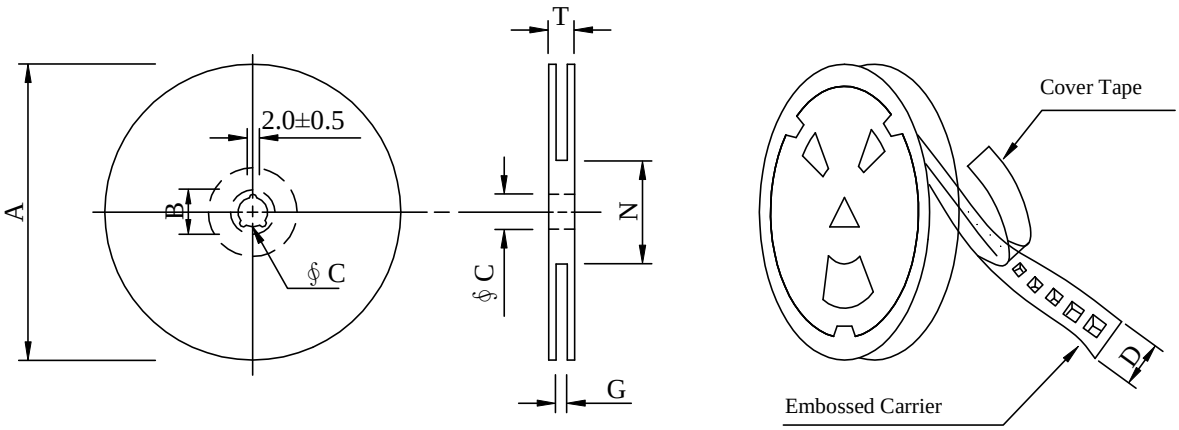
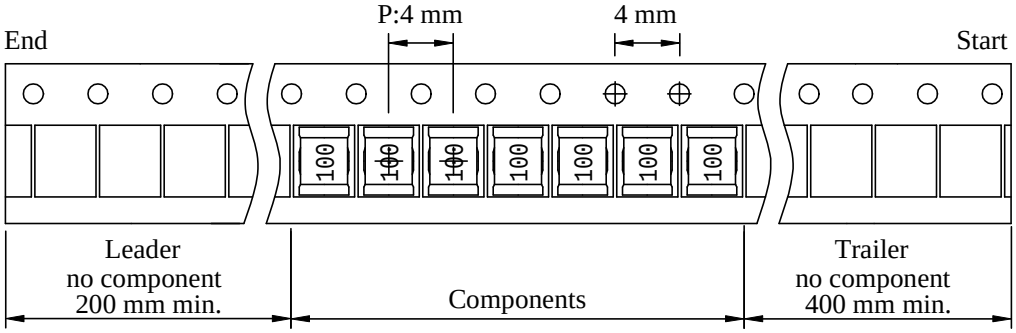
VI．Packaging information：

(1) Configuration



※Carrier Tape Width : D



User direction of feed

(2) Dimensions

Unit:mm

Style	A	B	C	D	G	N	T
07(S) - 08	183	21±0.8	13	8	10^{+0}	50^{-0}	12.5

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	2,000	190	07(S) - 08	100,000	11.15	42 x 41 x 24

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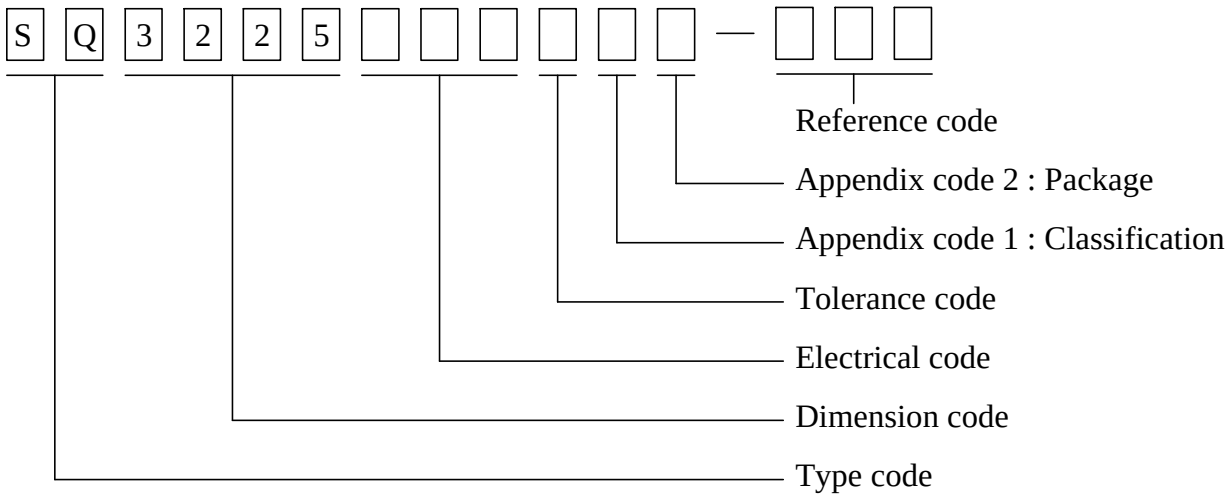
VII．Drawing number expression：



Appendix code 1：Product Classification

Appendix code 2：Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	UCT	Non-antistatic	Antistatic	2,000 pcs	

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VIII．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycles. 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature：85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃(Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperarance. 2.No marking blurred. 3.Inductance shall not change more than ±10%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature：260±5℃. 2.Time（temp.≧ 217℃）：60~150 Seconds. 3.IR reflow times：3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 seconds. 2.Saturation current	Inductance shall not drop more than 10% max.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 20 ℃ max.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing： 150±5℃ / 16Hours±30 min. 2.Peak temperature：240±5℃ 3.Time（temp.≧ 217℃）：60~150 seconds. 4.IR reflow times：1 time.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature：-40℃~125℃ 2.Room temperature：25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±10%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time：6 times (Every side of sample drop 2 times)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.